

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Error xs
1	BRS	L3	2887	circuit adj layer	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 13:34			0
2	BRS	L4	281	stress adj relax\$ adj layer	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 15:26			0
3	BRS	L5	0	L3 and L4	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 12:54			0
4	BRS	L6	5	L3 and (stress near layer)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 12:56			0
5	BRS	L7	63	L4 and (semiconductor or chip or die or wafer)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 12:58			0
6	BRS	L8	115	L4 and (semiconductor or chip or die or wafer)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 13:07			0
7	BRS	L9	11	L8 and porous	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 13:07			0
8	BRS	L10	57	(stress with (buffer adj layer))	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 13:26			0

	Type	L #	Hits	Search Text	Dbs	Time Stamp	Comments	Error Definition	Errors
9	BRS	L11	1	L10 and L13	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 13:32			0
10	BRS	L12	267	porous adj tape	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 13:33			0
11	BRS	L13	3	L3 and L12	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 13:33			0
12	BRS	L14	4	(chip with (buffer adj layer) or (stress with layer)) and (circuit adj layer)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 13:59			0
13	BRS	L15	269	organic near (protects adj film)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 14:03		Truncation Overflow. Return string from Server is: 5.956494	1
14	BRS	L16	98	L15 and (semis or chip)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 14:06		Truncation Overflow. Return string from Server is: 5.0.0.SEM	1
15	BRS	L17	8	L15 near (semis or chip or wafer)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 14:14		Truncation Overflow. Return string from Server is: 5.0.0.SEM	1
16	BRS	L18	48	L15 with (semis or chip or wafer)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 14:42		Truncation Overflow. Return string from Server is: 5.0.0.SEM	1

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
17	BRS	L19	369	((prevent or stop or less) near warps) with (chip or die or semiconductor or wafer)	USPAT; US--PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 14:46			0
18	BRS	L20	369	((prevent or stop or less) near warps) with (chip or die or semiconductor or wafer)	USPAT; US--PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 15:18			0
19	BRS	L21	39	L20 and ((porous or holes or spaces or gap) with layer)	USPAT; US--PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 15:20		Truncation Overflow. Return string from Server is: 5 318570`	1
20	BRS	L22	34	((porous or gap or space or hole) with ( stress adj ((relax\$ or buffer) adj layer))	USPAT; US--PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 16:31			0
21	BRS	L23	210113	((porous or gap or space or hole) with layer	USPAT; US--PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 16:39			0
22	BRS	L24	61972	L23 and (semiconductor or chip or wafer)	USPAT; US--PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 16:39			0
23	BRS	L25	372	L24 and (circuit adj layer)	USPAT; US--PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 16:40			0
24	BRS	L26	54767	porous with layer	USPAT; US--PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 16:39			0

Type	L #	Hits	Search Text	Dbs	Time Stamp	Comments	Error Definition	Errors
25 BRS	L27	4768	L26 and (semiconductor or chip or wafer)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 16:40			0
26 BRS	L28	29	L27 and (circuit adj layer)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 16:58			0
27 BRS	L29	3	(porous near (tape or polyimide)) and (circuit adj layer)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 17:00			0
28 BRS	L30	1381	L3 and (semiconductor or chip or wafer or die)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 17:56			0
29 BRS	L32	0	L31 and (circuit adj layer)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 17:59			0
30 BRS	L33	1	L31 and trace and (stress with layer)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 17:59			0
31 BRS	L31	51	257/669.ccls.	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 18:11			0
32 BRS	L34	1	L31 and (protects with (film or liner or layer))	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 18:07		Truncation Overflow. Return string from Server is: 5 0 0 PRO	1

	Type	L #	Hits	Search Text	Dbs	Time Stamp	Comments	Error Definition	Error Is
33	BRS	L35	1	L31 and liner	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 18:07			0
34	BRS	L36	5131	package with (close or "same" or size) with (chip or die)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 18:13			0
35	BRS	L37	344	package with (close or "same") with size with (chip or die)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 18:32			0
36	BRS	L38	16	L37 and warp	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 18:53			0
37	BRS	L39	110	L37 and stress	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 18:55			0
38	BRS	L40	103	L39 NOT L38	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 19:28			0
39	BRS	L41	1	"5258330".PN.	USPAT	2001/08/21 19:05			0
40	BRS	L42	1	"5477933".PN.	USPAT	2001/08/21 19:05			0
41	BRS	L43	1	"5627405".PN.	USPAT	2001/08/21 19:06			0
42	BRS	L44	1	"5684330".PN.	USPAT	2001/08/21 19:06			0
43	BRS	L45	1	"5759873".PN.	USPAT	2001/08/21 19:06			0
44	BRS	L46	1	"5786270".PN.	USPAT	2001/08/21 19:06			0

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
45	BRS	L47	1	tape adj absorb adj stress	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/08/21 19:30			0
46	BRS	L48	37	tape with (absorb\$ near stress)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/08/21 19:31		Truncation Overflow. Return string from Server is: 5'425640'	1

Type	L #	Hits	Search Text	Dbs	Time Stamp	Comments	Error Definition	Errors
1 BRS	L1	120	257/668.ccls. and wafer	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 20:01			0
2 BRS	L2	37	257/913.ccls. and wafer	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 20:02			0
3 BRS	L3	10	257/913.ccls. and stress	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 20:05			0
4 BRS	L4	1	(wafer adj (compris\$ or consists\$)) with (via adj hole)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 20:09			0
5 BRS	L5	6	(wafer adj (compris\$ or consists\$)) with ((via or through) adj hole)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 20:13			0
6 BRS	L6	120	257/668.ccls. and wafer	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 20:17			0
7 BRS	L7	92	257/635.ccls. and wafer	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 20:19			0
8 BRS	L8	53	257/635.ccls. and stress	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 20:29			0

	Type	L #	Hits	Search Text	Dbs	Time Stamp	Comments	Error Definition	Error Is
9	BRS	L9	21	257/638.ccls. and stress	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 20:32			0
10	BRS	L10	281	stress adj relaxs adj layer	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 20:33			0
11	BRS	L11	35	L10 and wafer	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 20:34			0
12	BRS	L12	7	L10 and package	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 20:36			0
13	BRS	L13	4063	porous with polytetrafluoroethylene	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 20:36			0
14	BRS	L14	1664	porous near polytetrafluoroethylene	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 20:37			0
15	BRS	L15	1431	porous adj polytetrafluoroethylene	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 20:37			0
16	BRS	L16	20	(porous adj polytetrafluoroethylene) same stress	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 20:43			0



Type	L #	Hits	Search Text	Dbs	Time Stamp	Comments	Error Definition	Errors
17 BRS	L17	496	ptfe same stress	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 20:44			0
18 BRS	L18	74	L17 and (semiconductor or chip or wafer)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 20:48			0
19 BRS	L19	632	resin with (via ad) hole)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 20:49			0
20 BRS	L20	10	(conduct\$ ad) resin) with (via ad) hole)	USPAT; US-PGPU B; EPO; JPO; DERMENT ; IBM TDB	2001/08/21 20:50		Truncation Overflow. Return string from Server is: 5'0'0'CON	1